



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Salman Akram

Serial No.: 09/388,031

Filed: September 1, 1999

For: METALLIZATION STRUCTURES
FOR SEMICONDUCTOR DEVICE
INTERCONNECTS, METHODS FOR
MAKING SAME, AND
SEMICONDUCTOR DEVICES
INCLUDING SAME

Confirmation No.: 3303

Examiner: E. Lee

Group Art Unit: 2815

Attorney Docket No.: 2269-3442.2US
96-0428.00/US

CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

October 20, 2004
Date

Signature

Leah Barrow
Name (Type/Print)

RESPONSE UNDER 37 C.F.R. §1.116

Mail Stop AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

The following remarks are filed in response to the Examiner's remarks in the Final Office Action mailed August 20, 2004, the three-month shortened statutory period for response to which expires on November 20, 2004. This response is submitted on or before two months from the mailing date of the Final Office Action.

Listing of the Claims begins on page 3 of this paper.

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Remarks/Arguments begin on page 12 of this paper.